

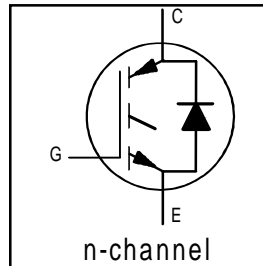
IRG4BC20SD-S

INSULATED GATE BIPOLAR TRANSISTOR WITH
 ULTRAFAST SOFT RECOVERY DIODE

Standard Speed IGBT

Features

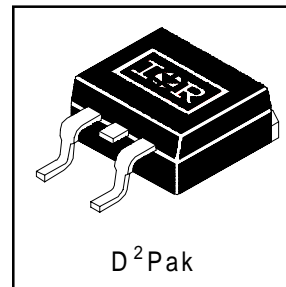
- Extremely low voltage drop 1.4Vtyp. @ 10A
- S-Series: Minimizes power dissipation at up to 3 KHz PWM frequency in inverter drives, up to 4 KHz in brushless DC drives.
- Very Tight Vce(on) distribution
- IGBT co-packaged with HEXFRED™ ultrafast, ultra-soft-recovery anti-parallel diodes for use in bridge configurations
- Industry standard D²Pak package



$V_{CES} = 600V$
$V_{CE(on)} \text{ typ.} = 1.4V$
@ $V_{GE} = 15V, I_C = 10A$

Benefits

- Generation 4 IGBT's offer highest efficiencies available
- IGBT's optimized for specific application conditions
- HEXFRED diodes optimized for performance with IGBT's . Minimized recovery characteristics require less/no snubbing
- Lower losses than MOSFET's conduction and Diode losses



Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	600	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	19	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	10	
I_{CM}	Pulsed Collector Current ①	38	
I_{LM}	Clamped Inductive Load Current ②	38	
$I_F @ T_C = 100^\circ C$	Diode Continuous Forward Current	7.0	
I_{FM}	Diode Maximum Forward Current	38	V
V_{GE}	Gate-to-Emitter Voltage	± 20	
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	60	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	24	
T_J	Operating Junction and	-55 to +150	°C
T_{STG}	Storage Temperature Range		

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case - IGBT	—	2.1	°C/W
$R_{\theta JC}$	Junction-to-Case - Diode	—	3.5	
$R_{\theta JA}$	Junction-to-Ambient (PCB Mounted,steady-state)*	—	80	
Wt	Weight	1.44	—	g (oz)

* When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
V _{(BR)CES}	Collector-to-Emitter Breakdown Voltage _f	600	—	—	V	V _{GE} = 0V, I _C = 250μA
dV _{(BR)CES} /dT _J	Temperature Coeff. of Breakdown Voltage	—	0.75	—	V/°C	V _{GE} = 0V, I _C = 1.0mA
V _{CE(on)}	Collector-to-Emitter Saturation Voltage	—	1.40	1.6	V	I _C = 10A
		—	1.85	—		I _C = 19A
		—	1.44	—		I _C = 10A, T _J = 150°C
V _{GE(th)}	Gate Threshold Voltage	3.0	—	6.0		V _{CE} = V _{GE} , I _C = 250μA
dV _{GE(th)} /dT _J	Temperature Coeff. of Threshold Voltage	—	-11	—	mV/°C	V _{CE} = V _{GE} , I _C = 250μA
g _{fe}	Forward Transconductance ④	2.0	5.8	—	S	V _{CE} = 100V, I _C = 10A
I _{CEs}	Zero Gate Voltage Collector Current	—	—	250	μA	V _{GE} = 0V, V _{CE} = 600V
		—	—	1700		V _{GE} = 0V, V _{CE} = 600V, T _J = 150°C
V _{FM}	Diode Forward Voltage Drop	—	1.4	1.7	V	I _C = 8.0A
		—	1.3	1.6		I _C = 8.0A, T _J = 150°C
I _{GES}	Gate-to-Emitter Leakage Current	—	—	±100	nA	V _{GE} = ±20V

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	
Q _g	Total Gate Charge (turn-on)	—	27	40	nC	I _C = 10A	
Q _{ge}	Gate - Emitter Charge (turn-on)	—	4.3	6.5		V _{CC} = 400V	
Q _{gc}	Gate - Collector Charge (turn-on)	—	10	15		V _{GE} = 15V	
t _{d(on)}	Turn-On Delay Time	—	62	—	ns	T _J = 25°C	
t _r	Rise Time	—	32	—		I _C = 10A, V _{CC} = 480V	
t _{d(off)}	Turn-Off Delay Time	—	690	1040		V _{GE} = 15V, R _G = 50Ω	
t _f	Fall Time	—	480	730		Energy losses include "tail" and diode reverse recovery.	
E _{on}	Turn-On Switching Loss	—	0.32	—		mJ	See Fig. 9, 10, 11, 18
E _{off}	Turn-Off Switching Loss	—	2.58	—			
E _{ts}	Total Switching Loss	—	2.90	4.5			
t _{d(on)}	Turn-On Delay Time	—	64	—		ns	T _J = 150°C, See Fig. 10, 11, 18
t _r	Rise Time	—	35	—			I _C = 10A, V _{CC} = 480V
t _{d(off)}	Turn-Off Delay Time	—	980	—			V _{GE} = 15V, R _G = 50Ω
t _f	Fall Time	—	800	—	Energy losses include "tail" and diode reverse recovery.		
E _{ts}	Total Switching Loss	—	4.33	—	mJ		
L _E	Internal Emitter Inductance	—	7.5	—	nH	Measured 5mm from package	
C _{ies}	Input Capacitance	—	550	—	pF	V _{GE} = 0V	
C _{oes}	Output Capacitance	—	39	—		V _{CC} = 30V	
C _{res}	Reverse Transfer Capacitance	—	7.1	—		f = 1.0MHz	
t _{rr}	Diode Reverse Recovery Time	—	37	55	ns	T _J = 25°C See Fig. 14	
		—	55	90		T _J = 125°C	
I _{rr}	Diode Peak Reverse Recovery Current	—	3.5	5.0	A	T _J = 25°C See Fig. 15	
		—	4.5	8.0		T _J = 125°C	
Q _{rr}	Diode Reverse Recovery Charge	—	65	138	nC	T _J = 25°C See Fig. 16	
		—	124	360		T _J = 125°C	
di _(rec) M/dt	Diode Peak Rate of Fall of Recovery During t _b	—	240	—	A/μs	T _J = 25°C See Fig. 17	
		—	210	—		T _J = 125°C	

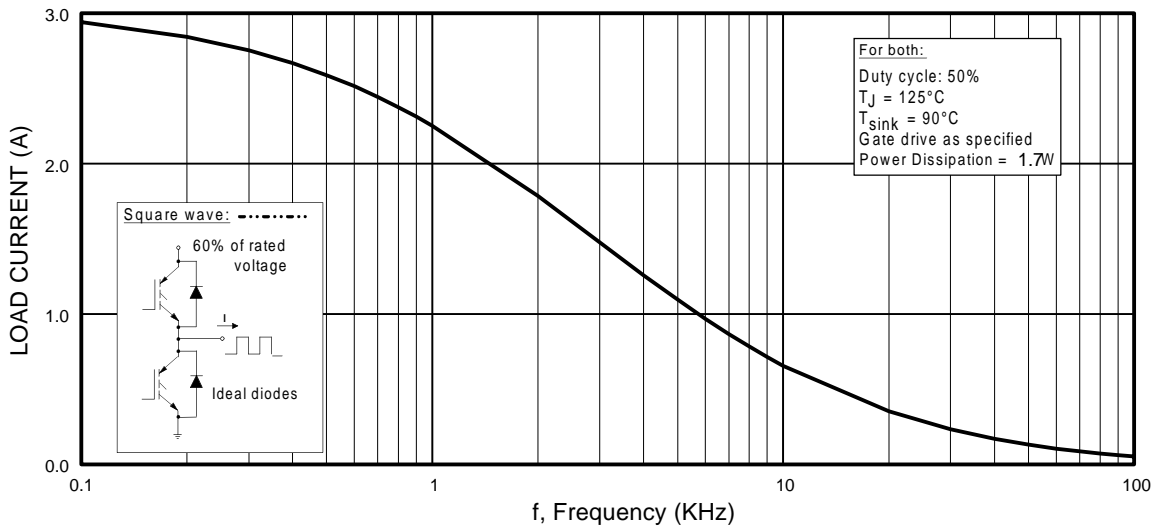


Fig. 1 - Typical Load Current vs. Frequency
 (Load Current = I_{RMS} of fundamental)

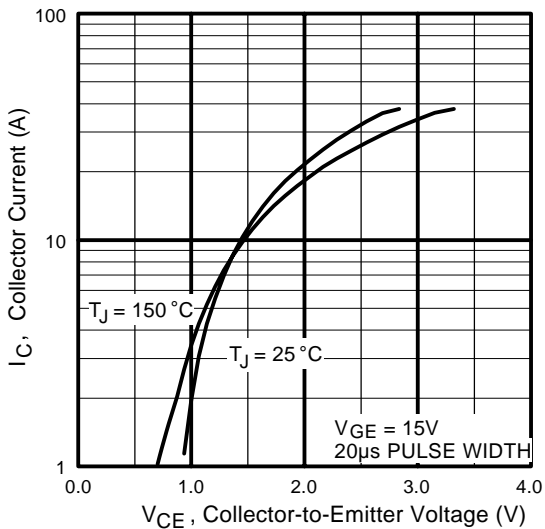


Fig. 2 - Typical Output Characteristics

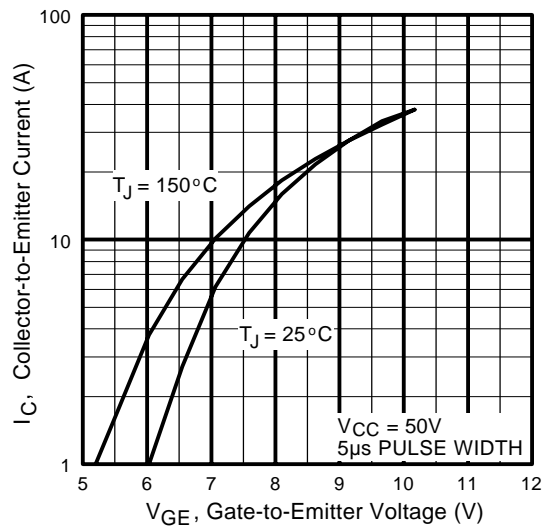


Fig. 3 - Typical Transfer Characteristics

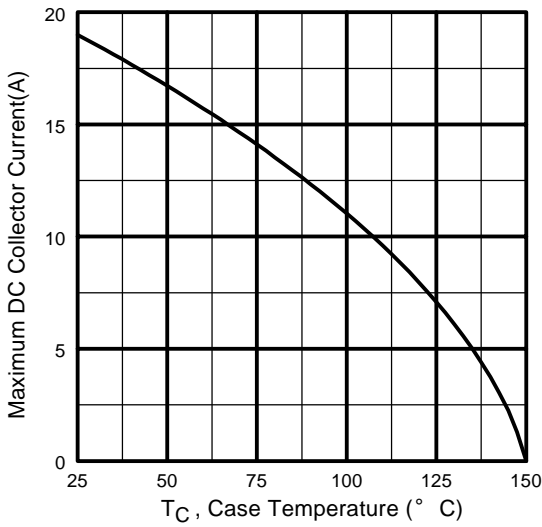


Fig. 4 - Maximum Collector Current vs. Case Temperature

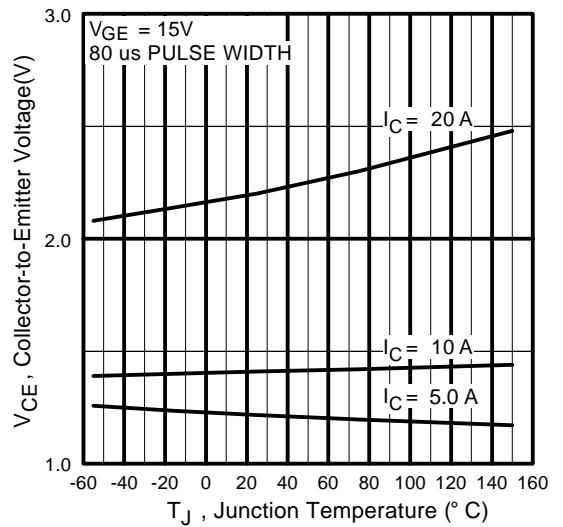


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

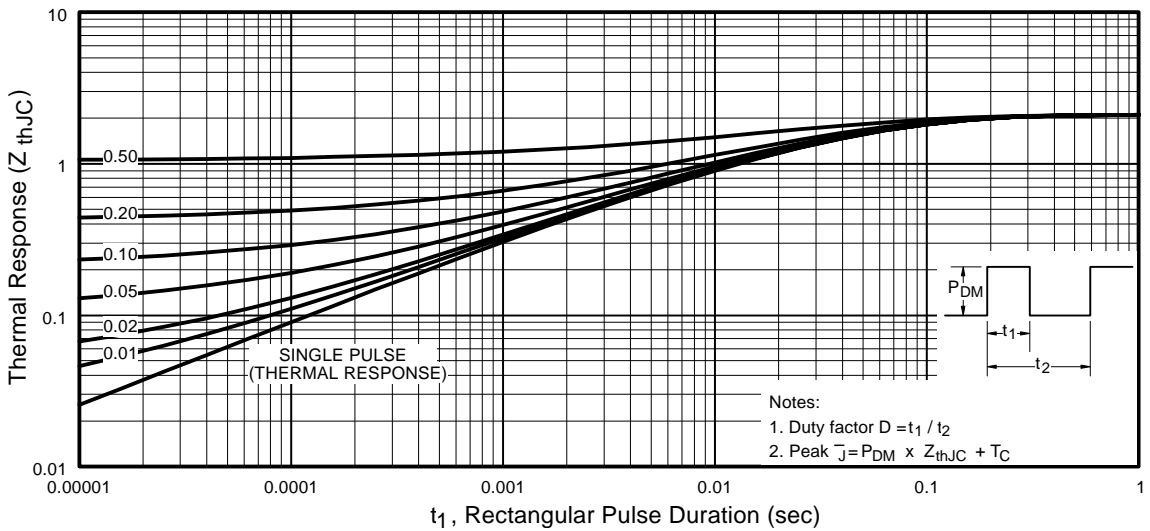


Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

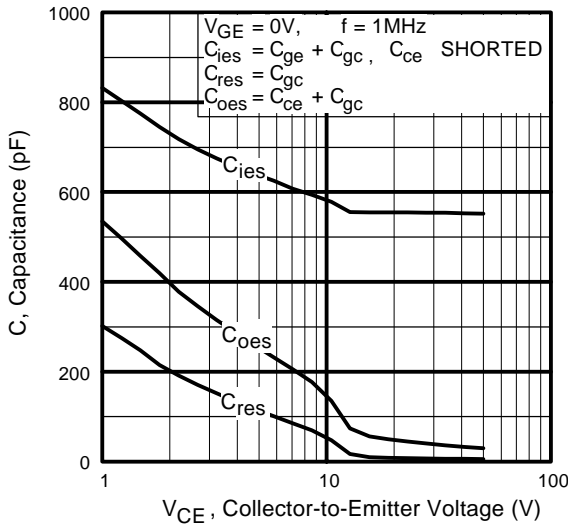


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

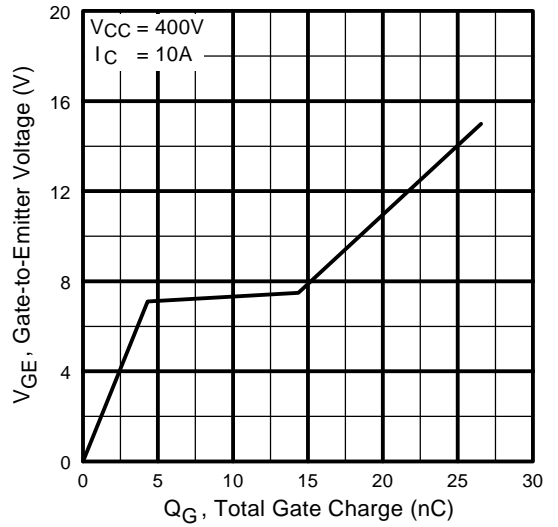


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage

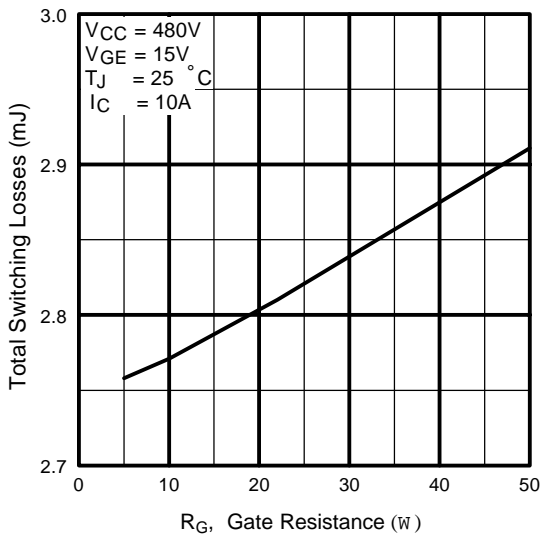


Fig. 9 - Typical Switching Losses vs. Gate Resistance

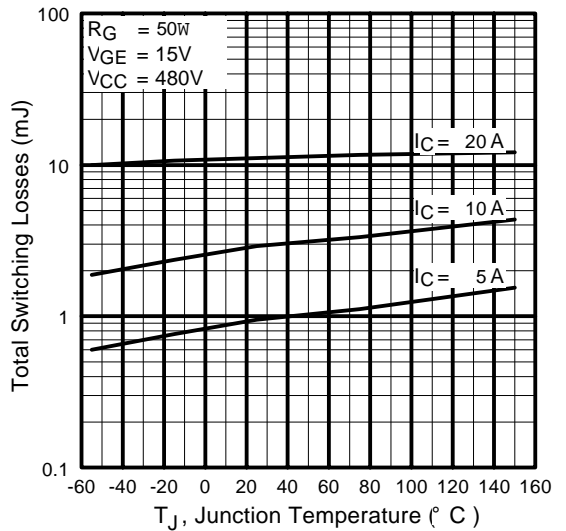


Fig. 10 - Typical Switching Losses vs. Junction Temperature

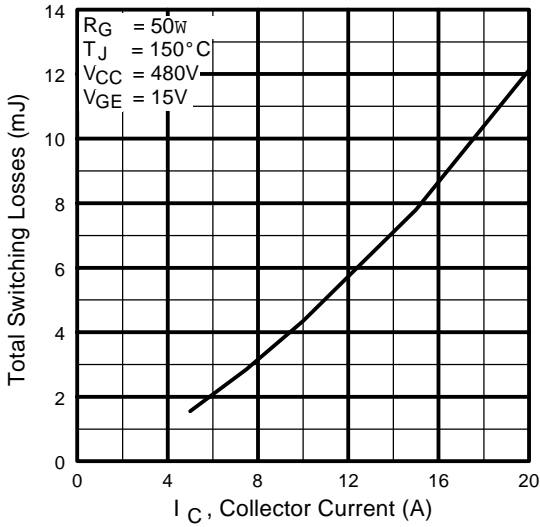


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

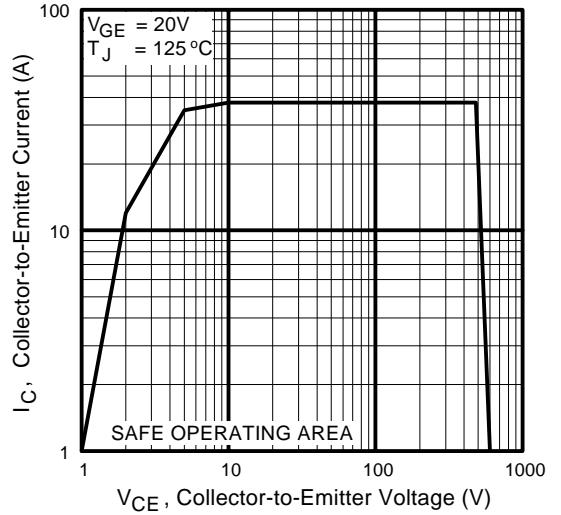


Fig. 12 - Turn-Off SOA

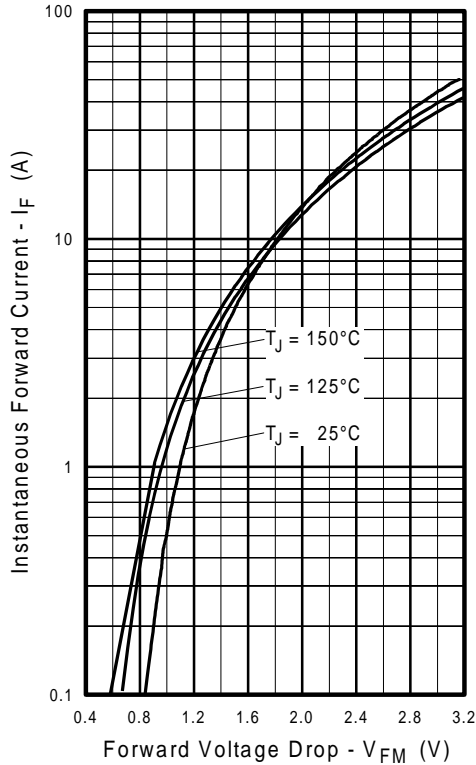


Fig. 13 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

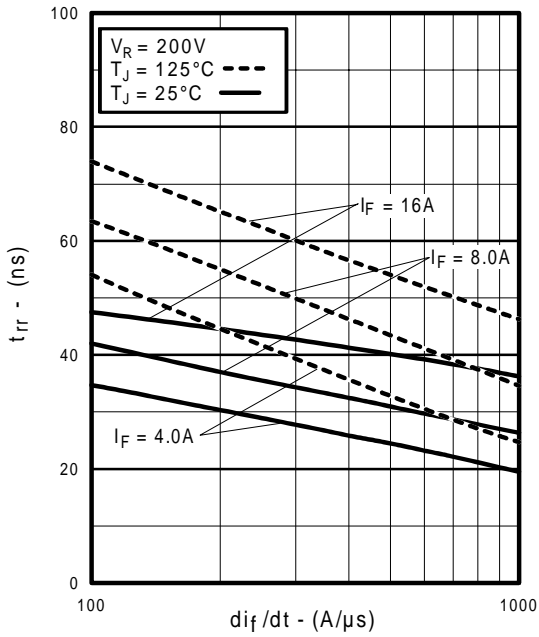


Fig. 14 - Typical Reverse Recovery vs. di_f/dt

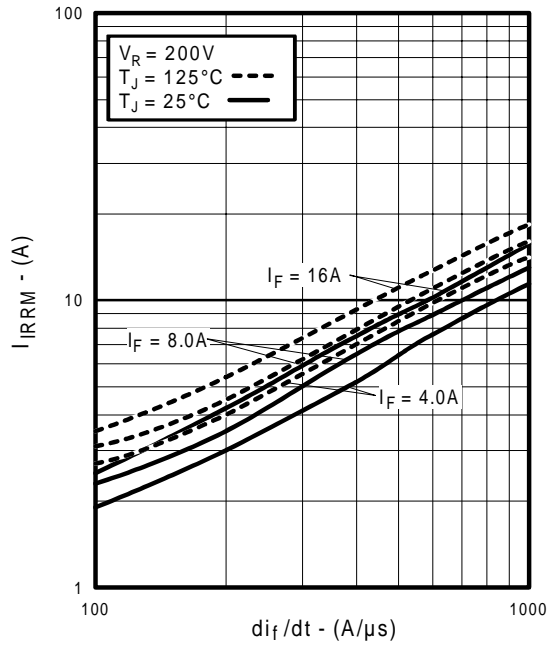


Fig. 15 - Typical Recovery Current vs. di_f/dt

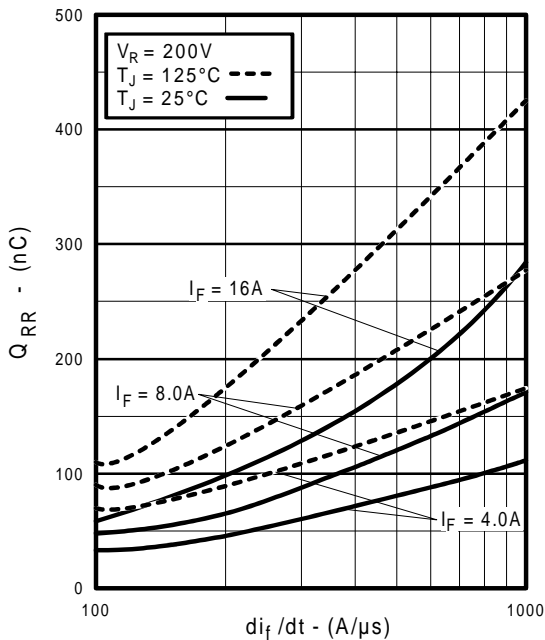


Fig. 16 - Typical Stored Charge vs. di_f/dt
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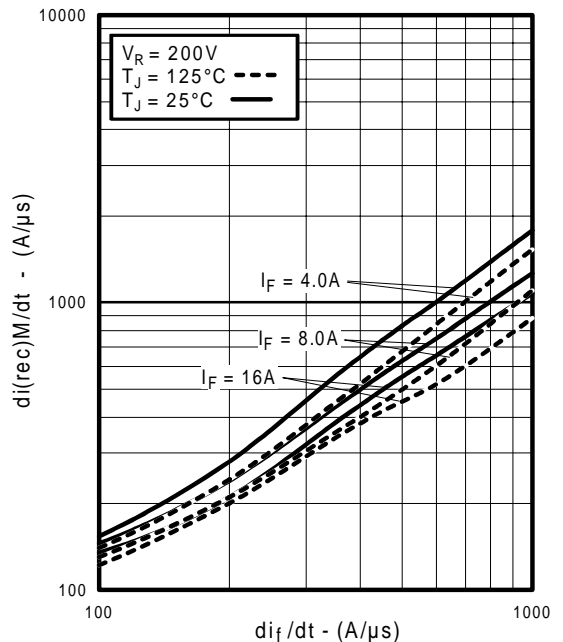


Fig. 17 - Typical $di_{(rec)M}/dt$ vs. di_f/dt

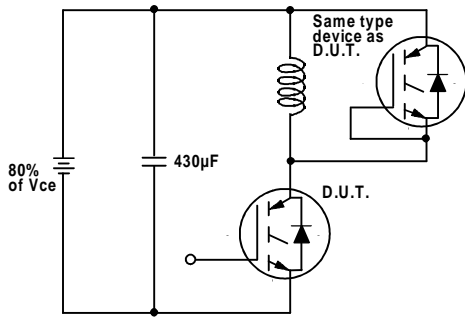


Fig. 18a - Test Circuit for Measurement of I_{LM} , E_{on} , $E_{off}(\text{diode})$, t_{rr} , Q_{rr} , I_{rr} , $t_{d(on)}$, t_r , $t_{d(off)}$, t_f

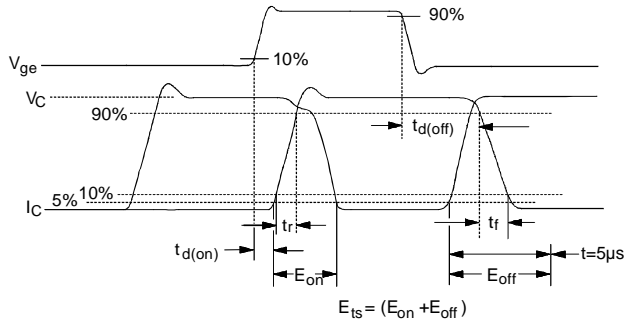


Fig. 18b - Test Waveforms for Circuit of Fig. 18a, Defining E_{off} , $t_{d(off)}$, t_f

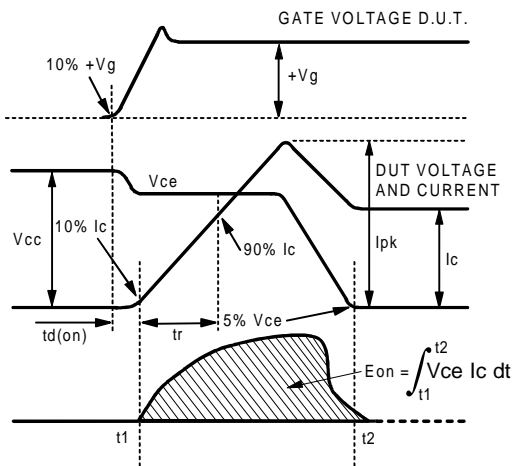


Fig. 18c - Test Waveforms for Circuit of Fig. 18a, Defining E_{on} , $t_{d(on)}$, t_r

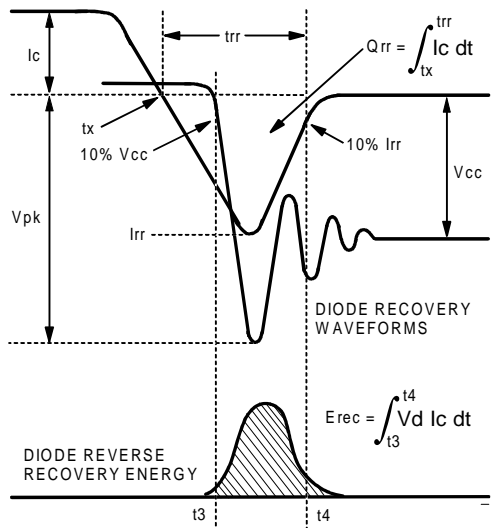


Fig. 18d - Test Waveforms for Circuit of Fig. 18a, Defining E_{rec} , t_{rr} , Q_{rr} , I_{rr}

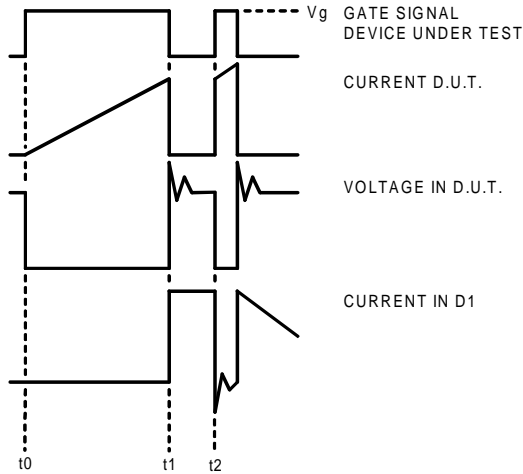


Figure 18e. Macro Waveforms for Figure 18a's Test Circuit

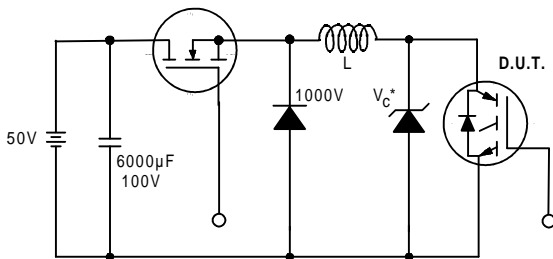


Figure 19. Clamped Inductive Load Test Circuit

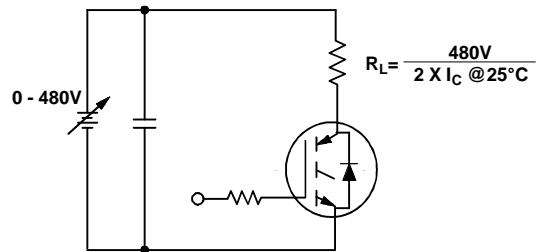
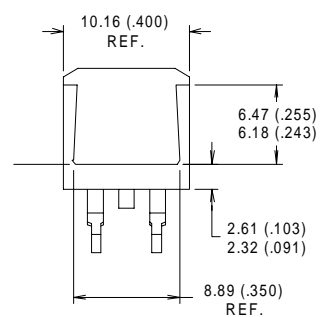
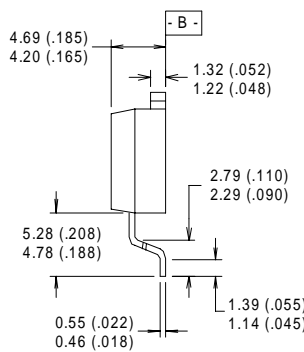
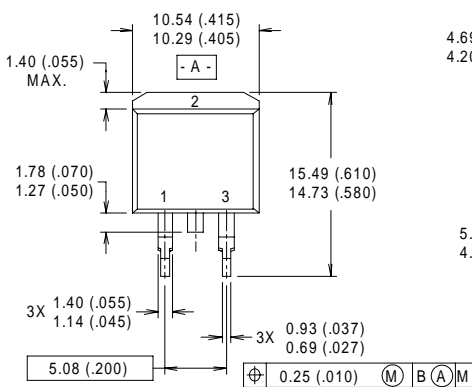


Figure 20. Pulsed Collector Current Test Circuit

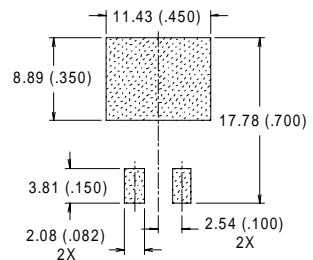
Notes:

- ① Repetitive rating: $V_{GE}=20V$; pulse width limited by maximum junction temperature (figure 20)
- ② $V_{CC}=80\% (V_{CES})$, $V_{GE}=20V$, $L=10\mu H$, $R_G = 50\omega$ (figure 19)
- ③ Pulse width $\leq 80\mu s$; duty factor $\leq 0.1\%$.
- ④ Pulse width $5.0\mu s$, single shot.

D²Pak Package Outline



MINIMUM RECOMMENDED FOOTPRINT



NOTES:

- 1 DIMENSIONS AFTER SOLDER DIP.
- 2 DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982.
- 3 CONTROLLING DIMENSION : INCH.
- 4 HEATSINK & LEAD DIMENSIONS DO NOT INCLUDE BURRS.

LEAD ASSIGNMENTS

- 1 - GATE
- 2 - DRAIN
- 3 - SOURCE

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